MA3J741DG, MA3J741EG

Silicon epitaxial planar type

For high speed switching For wave detection

■ Features

- Two MA3J7410G is contained in one package
- Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V _{RM}	30	V
Forward current	Single	I_{F}	30	mA
	Double		20	
Peak forward current	Single	I_{FM}	150	mA
	Double		110	1011
Junction temperature		Tj	125	°C
Storage temperature		T _{stg}	-55 to +125	C C

Package

- Code
 - SMini3-F2
- Pin Name

MA3J741DG MA3J741EG
1: Cathode 1 1: Anode 1
2: Cathode 2 2: Anode 2
3: Anode 3: Cathode

■ Marking Symbol

MA3J741DG: M2P MA3J741EG: M2R

Internal Connection

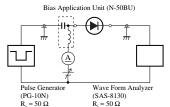




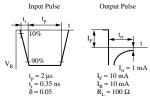
■ Electrical Characteristics T_a = 25°C ± 3°C

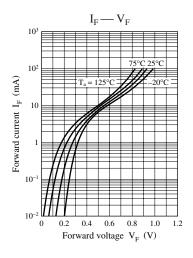
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	I _F = 1 mA	0,0,		0.4	V
	V_{F2}	I _F = 30 mA			1.0	
Reverse current	I _R	$V_R = 30 \text{ V}$			1	μΑ
Terminal capacitance	C _t	V _R = 1 V, f = 1 MHz		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
NA!		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, $f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

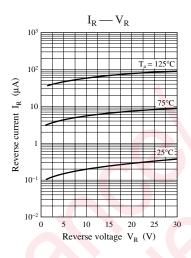
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 2 GHz.

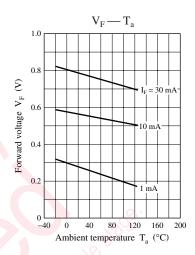


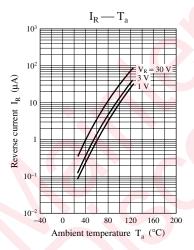
4.*: t_{rr} measurement circuit

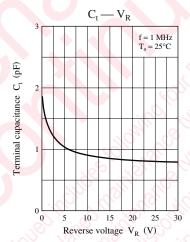


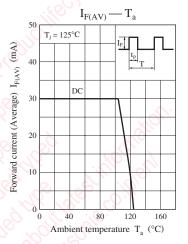






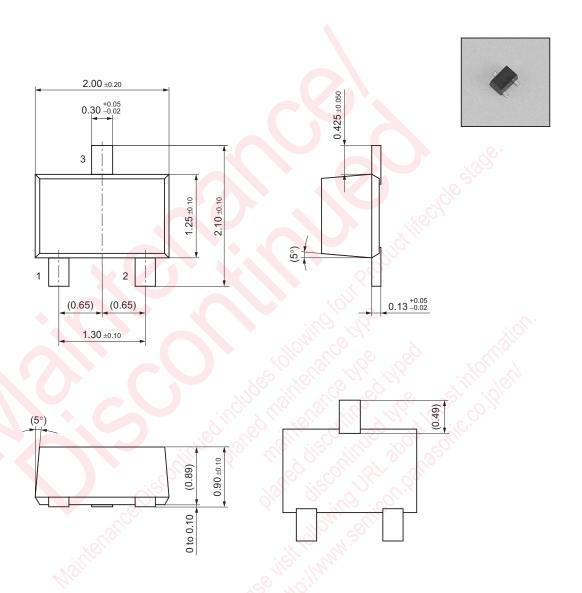






2 SKH00195AED

SMini3-F2 Unit: mm



SKH00195AED 3

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